Potting Compounds and Encapsulants
Reliable Protection of Components
# The Perfect Product for Your Potting or Encapsulation Project

<table>
<thead>
<tr>
<th>Application focus</th>
<th>Rigid potting compounds and encapsulants</th>
<th>Permanently flexible potting compounds and encapsulants</th>
</tr>
</thead>
<tbody>
<tr>
<td>Dam &amp; fill, glob top</td>
<td>✓</td>
<td>×</td>
</tr>
<tr>
<td>Partial encapsulation</td>
<td>✓</td>
<td>×</td>
</tr>
<tr>
<td>Full encapsulation</td>
<td>✓</td>
<td>×</td>
</tr>
<tr>
<td>Large-volume potting</td>
<td>×</td>
<td>✓</td>
</tr>
</tbody>
</table>

## Application example (encapsulants represented in magenta in all illustrations)

## Number of components / chemical basis
- 1C anhydride
- 2C anhydride

## Curing
- Heat, light fixation optional
- Heat

## Product group
- DELO MONOPOX
- DELO DUALBOND
- DELO-DUOPOX
- DELO KATIOBOND
- DELO PHOTOBOND

## Product features
- High reliability
- Excellent media and temperature resistance
- High reliability
- Long processing time at room temperature

## Temperature of continuous use [°C]
- Up to +250
- +180

## Min. curing temperature [°C]
- +100 resp. +120 (DELO DUALBOND)
- +130

## Shortest curing time
- 20 min (+180 °C)
- 20 min (+150 °C)

## Coefficient of linear expansion CTE [ppm/K]
- 11 to 60
- 18 to 35

## Glass transition temperature $T_g$ [°C]
- +150 to +200
- +165 to +180

## Young's modulus [MPa]
- 8,000 to 12,000
- 6,000 to 8,000

## Elongation at tear [%]
- < 1
- < 1

## Media resistance
- +++
- ++

## Transparency possible
- 

## Purity
- Halogen-free
- Low outgassing
- Low outgassing

## Details
- P. 4/5
- P. 6
DELO offers high-tech adhesives tailored to meet the specific needs of any industrial application. Our wide range of products allows us to satisfy any requirement. Light-curing, heat-curing, or dual-curing, soft or hard, transparent or black – DELO has the ideal adhesive for any potting and encapsulation process.

Dr. Karl Bitzer, Head of Product Management

<table>
<thead>
<tr>
<th></th>
<th>Permanently flexible potting compounds and encapsulants</th>
</tr>
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<tbody>
<tr>
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<td>✗</td>
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</tbody>
</table>

<table>
<thead>
<tr>
<th>1C epoxy</th>
<th>2C epoxy</th>
<th>1C epoxy</th>
<th>1C acrylate</th>
</tr>
</thead>
<tbody>
<tr>
<td>light and/or heat</td>
<td>room temperature, heat optional</td>
<td>light and/or heat</td>
<td>light, light and, or heat</td>
</tr>
<tr>
<td>DELO KATIOBOND</td>
<td>DELO-DUPOX</td>
<td>DELO KATIOBOND</td>
<td>DELO PHOTOBOND</td>
</tr>
<tr>
<td>fast curing</td>
<td>curing at room temperature</td>
<td>fast curing</td>
<td>curing within seconds</td>
</tr>
<tr>
<td>+180 to +200</td>
<td>large containers</td>
<td>long processing time</td>
<td>immediate final strength</td>
</tr>
<tr>
<td>+80 or light curing</td>
<td>easy transport and storage</td>
<td></td>
<td></td>
</tr>
<tr>
<td>room temperature</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>&lt; 10 s</td>
<td>5 min (+80 °C)</td>
<td>&lt; 10 s</td>
<td>&lt; 10 s</td>
</tr>
<tr>
<td>13 to 52</td>
<td>80 to 280</td>
<td>200 to 300</td>
<td>approx. 200</td>
</tr>
<tr>
<td>+130 to +200</td>
<td>room temperature up to +80</td>
<td>−40 to +50</td>
<td>−60 to +100</td>
</tr>
<tr>
<td>3,000 to 23,000</td>
<td>20 to 1,500</td>
<td>10 to 1,000</td>
<td>1 to 500</td>
</tr>
<tr>
<td>&lt; 2</td>
<td>5 to 70</td>
<td>10 to 120</td>
<td>150 to 500</td>
</tr>
<tr>
<td>++</td>
<td>+</td>
<td>+</td>
<td></td>
</tr>
<tr>
<td>RoHS-compliant</td>
<td>unfilled possible</td>
<td>halogen-free</td>
<td>halogen-free</td>
</tr>
<tr>
<td>low outgassing</td>
<td></td>
<td>RoHS-compliant</td>
<td>RoHS-compliant</td>
</tr>
<tr>
<td></td>
<td></td>
<td>unfilled</td>
<td>unfilled</td>
</tr>
</tbody>
</table>

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Heat-curing Encapsulants for Chips and Sensors

Unique combination of high reliability and outstanding processing properties

It is essential that electronic components, such as chips and sensors, work properly in the most diverse fields of application, even under extreme conditions. Sensors used, for example, to check the oil level or pressure must be highly resistant to aggressive media and elevated temperatures. Specifically for such applications, we have developed encapsulants based on anhydride-curing epoxy resins, featuring outstanding media and temperature resistance. The optimized flow behavior and various curing options of these adhesives provide additional benefits in terms of efficient production processes.

Application areas

- Automotive, e.g. sensor encapsulation
- Power electronics, e.g. rectifiers
- Industry, e.g. print heads
- Consumer electronics, e.g. sensor encapsulation
- Medical technology

Customer’s benefits

- Flowability adjusted to your application, e.g. stable dam and flowable fill
- Excellent properties for partial and full encapsulation
- Dam and fill curing in one step for an efficient production process
- Variable curing parameters (fast curing or low curing temperature) for optimized processes

Product properties

- 1C anhydrides and 1C epoxy (DELO MONOPOX, DELO DUALBOND)
- Color: Black (transparency and coloring possible)
- Temperature of use ranging from –65 to +180°C or +250°C, respectively
- Very low CTE (11 – 60 ppm/K) for minimum warpage and reduced stress on the components
- Excellent resistance to media and temperatures
High temperature resistance up to +250 °C

- Temperature of use ranging from –65 to +250°C
- Very good temperature resistance and temperature stability
- Very good bond strength

Light fixation in seconds

- Fast and reliable processes: Fixation within seconds, easy handling of the fixed components, final curing by heat (e.g. 30 min at +150°C)
- Defined, highly accurate encapsulation in tiny spaces (no flowing)
- Viscosities available for different applications (e.g. glob top, bonding, dam)

Delicate structures and large-area encapsulation

- Efficient protection of the individual components
- Small-sized fillers for narrow wire spacing and cavities
- Dam: Stack of fine adhesive beads featuring high flow resistance and an aspect ratio of up to 2.5
- Fill: Good flow behavior combined with a low CTE
Safe and reliable protection of sensors

The automotive sector, in particular, makes high demands on encapsulants regarding excellent resistance to media such as petrol, diesel or oil as well as to temperatures. The two-component heat-curing DELO-DUOPOX CR types (CR = Casting Resin) clearly meet these requirements and stand out with excellent flow properties and rapid curing in an air convection oven as well as simple logistics.

Application areas

- Sensors, e.g. for the automotive industry
- General industrial electric and electronic products
- Machinery and equipment industry

Product properties

- 2C anhydrides (DELO-DUOPOX CR)
- Black, opaque even in thin layers
- Curing at +130 to +180 °C (e.g. 20 min at +150 °C in an air convection oven)
- Very low CTE (18 – 35 ppm/K) for minimum warpage and reduced stress on the components
- Very good media resistance (e.g. to fluids in vehicles, harmful gases)
- Very good temperature resistance
- Good adhesion to plastic and metal

Customer’s benefits

- Reduced assembly size: The adhesive’s outstanding media resistance allows electronic components to be directly installed in units (e.g. in a gearbox in the ATF)
- Flexible processing options:
  - Manual processing or (fully) automated processes
  - Excellent flow properties for easy dispensing and short cycle times
  - Flow behavior adjustment by heating the components in the system
- Economic packaging and logistics thanks to larger containers, easy and cost-efficient transport, and storage at room temperature

Heat-curing Compounds for Large-scale Encapsulation
Defined encapsulation to protect electronic components

The light-fixable one-component epoxy resins are primarily used when bonded or encapsulated components are exposed to extreme temperatures and aggressive media. Brief light fixation enables greater bonding accuracy, a defined fillet, and easier handling of the fixed components. Glob top encapsulation additionally allows "freezing the shape", since the skin formed prevents the compound from flowing during subsequent heat curing.

Application areas

- Polymeric protection system
- Encapsulation, coating, and mounting of microelectronics
- Smart cards

Customer’s benefits

- Short cycle times thanks to
  - Light curing within seconds (DELO KATOBOND)
  - Light fixation, fast and reliable curing at low temperatures from +80°C even in shadowed areas (DELO DUALBOND)
- Simple processing
- Long processing time (> 5 days) at room temperature
- Availability in large containers (up to 10 kg) makes packaging and logistics economical

Product properties

- 1C epoxy (DELO KATOBOND, DELO DUALBOND, DELO MONOPOX)
- Color: Variable
- Very low CTE (13 – 52 ppm/K) for minimum warping and reduced stress on the components
- Very good media and temperature resistance
- Low outgassing

Glob top encapsulation
Simple processing at room temperature

DELO-DUOPOX two-component encapsulants distinguish themselves by easy processing, energy-efficient curing, and simple logistics. Different hardener systems provide diverse product properties.

Application areas

- Sensors, e.g. for the automotive industry
- General industrial electric and electronic products
- Machinery and equipment industry

Product properties

- 2C epoxy (DELO-DUOPOX)
- Color: Yellowish translucent, black
- Curing at room temperature or accelerated curing at +60 to +80°C (e.g. 1 h at +80°C in air convection oven)
- Reactivity ranging from fast curing to long processing time for large volumes
- From flexible and tension-equalizing to tough-hard
- Very good media resistance (e.g. to fluids in vehicles, harmful gases)
- Good adhesion to plastic and metal

Customer’s benefits

- Simple, economic processing at room temperature
- Flexible processing options:
  - Manual processing or (fully) automated processes
  - Excellent flow properties for easy dispensing and short cycle times
  - Flow behavior adjustment by heating the components in the system
- Simplified component design: Sealing of status LEDs or similar components in clear or translucent colors allows additional components to be dispensed with
- Economic packaging and logistics thanks to larger containers, easy and cost-efficient transport, and storage at room temperature

Flexible Compounds for Large-volume Encapsulation

Encapsulation of electronic circuit carriers to protect its individual components

Material selection guides
“Adhesives for Automotive Sensors”
“Encapsulants”
Fixation within seconds for rapid further processing

DELO KATIOBOND and DELO DUALBOND, the flexible and light-fixable one-component epoxy resins, protect sensors and other electronic components reliably against thermal influences, media, and vibrations, while still enabling cycle times < 10 s.

Application areas

- Sensor encapsulation, e.g. Hall sensor (see figure)
- Sealing of sensors
- Encapsulation of control electronics or other electronic components

Customer’s benefits

- Short cycle times thanks to light fixation within seconds with DELOLUX LED lamps
- Process reliability thanks to reliable curing in shadowed areas at only +120 °C
- A convenient processing time of several days or weeks at room temperature simplifies the production process
- Improved functionality: Reliable protection of components against thermal influences, media, and vibrations

Product properties

- 1C epoxy (DELO KATIOBOND, DELO DUALBOND)
- Color: Yellowish, transparent
- Light fixation in < 10 s for immediate further processing, curing to final strength within 24 h (DELO KATIOBOND) or accelerated heat-curing within a few minutes (DELO DUALBOND)
- Flexible and tension-equalizing, even in case of thermal stress
- Good media resistance (e.g. to oil, petrol, brake fluid, salt spray test)
- Good temperature resistance
- Dry surface
Sealing of Switches and Plugs

Curing within seconds ensures short cycle times

DELO PHOTOBOND and DELO DUALBOND, the light-curing one-component acrylates, guarantee reliable sealing of microswitches and plugs, fixation of electronic components, and bonding of housing parts. Fast bonding processes combining short cycle times and reliable process control are particularly important for applications in the automotive sector.

Application areas

- Sensors
- Microswitches
- Plugs
e.g. for the automotive industry

Product properties

- 1C acrylate (DELO PHOTOBOND, DELO DUALBOND)
- Color: Variable, fluorescence optional
- Light-curing in < 10 s, immediate final strength
- Highly flexible and tension-equalizing
- Good temperature resistance

Customer’s benefits

- Direct quality control (in-line quality control) saves time and costs
- Ideal for fully automated production lines
- No thermal stress applied to components
- Process reliability thanks to reliable curing in shadowed areas (curing in the presence of heat or humidity, depending on the product)
- Optimally suited for hybrid and plastic bonding

Material selection guide
“Sealing of Electromechanical Components”
DELOLUX LED lamps are the leading technology when it comes to fast curing and allow optimal adjustment to the adhesive used. They have a high energy efficiency and can achieve a service life of more than 20,000 hours, which is significantly higher than that of conventional discharge lamps. For optimal curing, the wavelengths are adjusted to the adhesive properties. The lamps stand out for their low power consumption and allow the lamp power to be set individually. All these additional features guarantee cost-efficient production processes.

Curing within Seconds with DELOLUX

<table>
<thead>
<tr>
<th>LED lamp</th>
<th>DELOLUX 80</th>
<th>DELOLUX 20</th>
<th>DELOLUX 820</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Description</strong></td>
<td>High-intensity area lamp for small bonding areas</td>
<td>High-intensity area lamp for homogeneous irradiation</td>
<td>Area lamp for homogeneous irradiation</td>
</tr>
</tbody>
</table>
| **Light exit area** | 365 nm: 23.0 mm dia.  
                          400 nm: 23.0 mm dia.  
                          460 nm: 16.9 mm dia. | DELOLUX 20:  
                          100 mm × 100 mm  
                          DELOLUX 202:  
                          202 mm × 49 mm | x4: 848 mm × 30 mm  
                          x6: 1,250 mm × 30 mm |
| **Wavelength/typ. intensity** | 365 nm: ≥ 4,000 mW/cm²  
                               400 nm: ≥ 5,500 mW/cm²  
                               460 nm: ≥ 2,500 mW/cm² | 365 nm (A1): ≥ 600 mW/cm²  
                               365 nm (A2): ≥ 1,200 mW/cm²  
                               400 nm (A1): ≥ 1,000 mW/cm²  
                               400 nm (A2): ≥ 2,000 mW/cm²  
                               460 nm (A1): ≥ 1,000 mW/cm²  
                               460 nm (A2): ≥ 2,000 mW/cm² | 365 nm: ≥ 250 mW/cm² |
| **Reliability**   | Intensity measurement with DELOLUXcontrol | | |

Curing of a glob top encapsulant with DELOLUX 80
The data and information provided are based on tests performed under laboratory conditions. Reliable information about the behavior of the product under practical conditions and its suitability for a specific purpose cannot be concluded from this. It is the customer’s responsibility to test the suitability of a product for the intended purpose by considering all specific requirements and by applying standards the customer deems suitable (e.g. DIN 2304-1). Type, physical and chemical properties of the materials to be processed with the product, as well as all actual influences occurring during transport, storage, processing and use, may cause deviations in the behavior of the product compared to its behavior under laboratory conditions. The data and information provided are therefore no guarantee for specific product properties or the suitability of the product for a specific purpose. Nothing contained herein shall be construed to indicate the non-existence of any relevant patents or to constitute a permission, encouragement or recommendation to practice any development covered by any patents, without permission of the owner of this patent. All products provided by DELO are subject to DELO’s General Terms of Business. Verbal ancillary agreements are deemed not to exist.

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